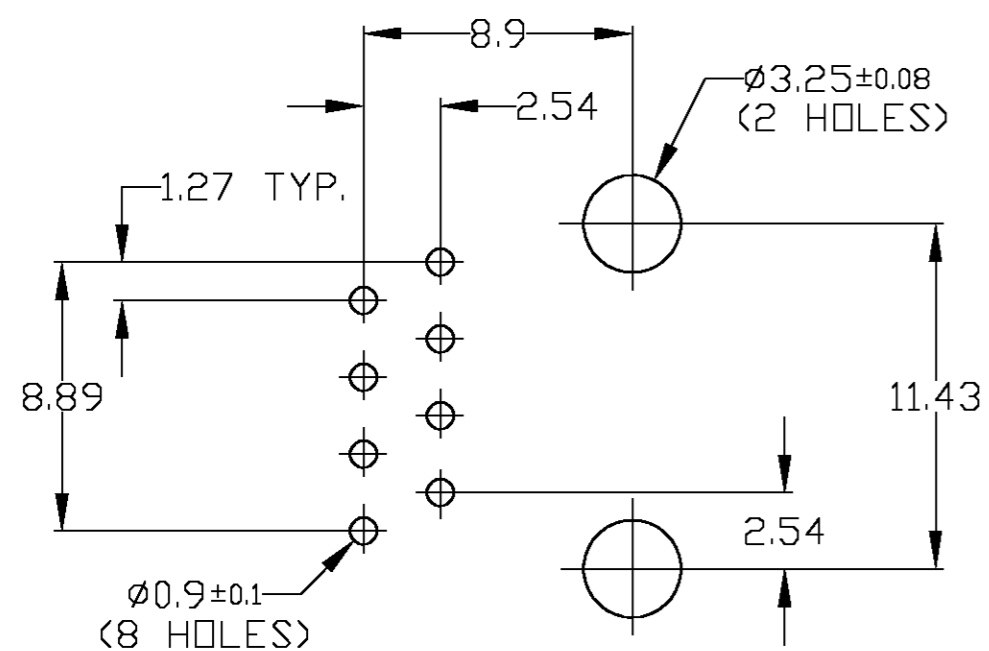
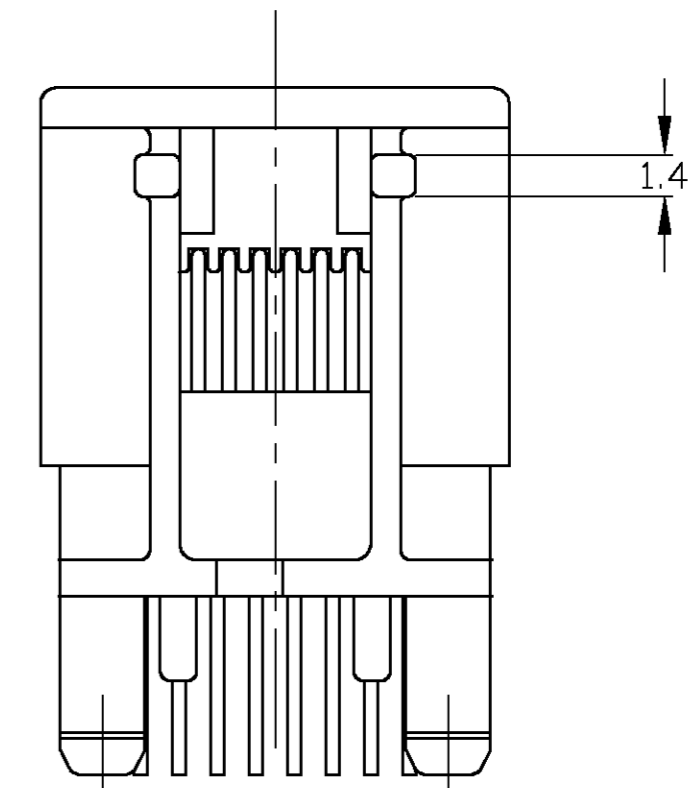
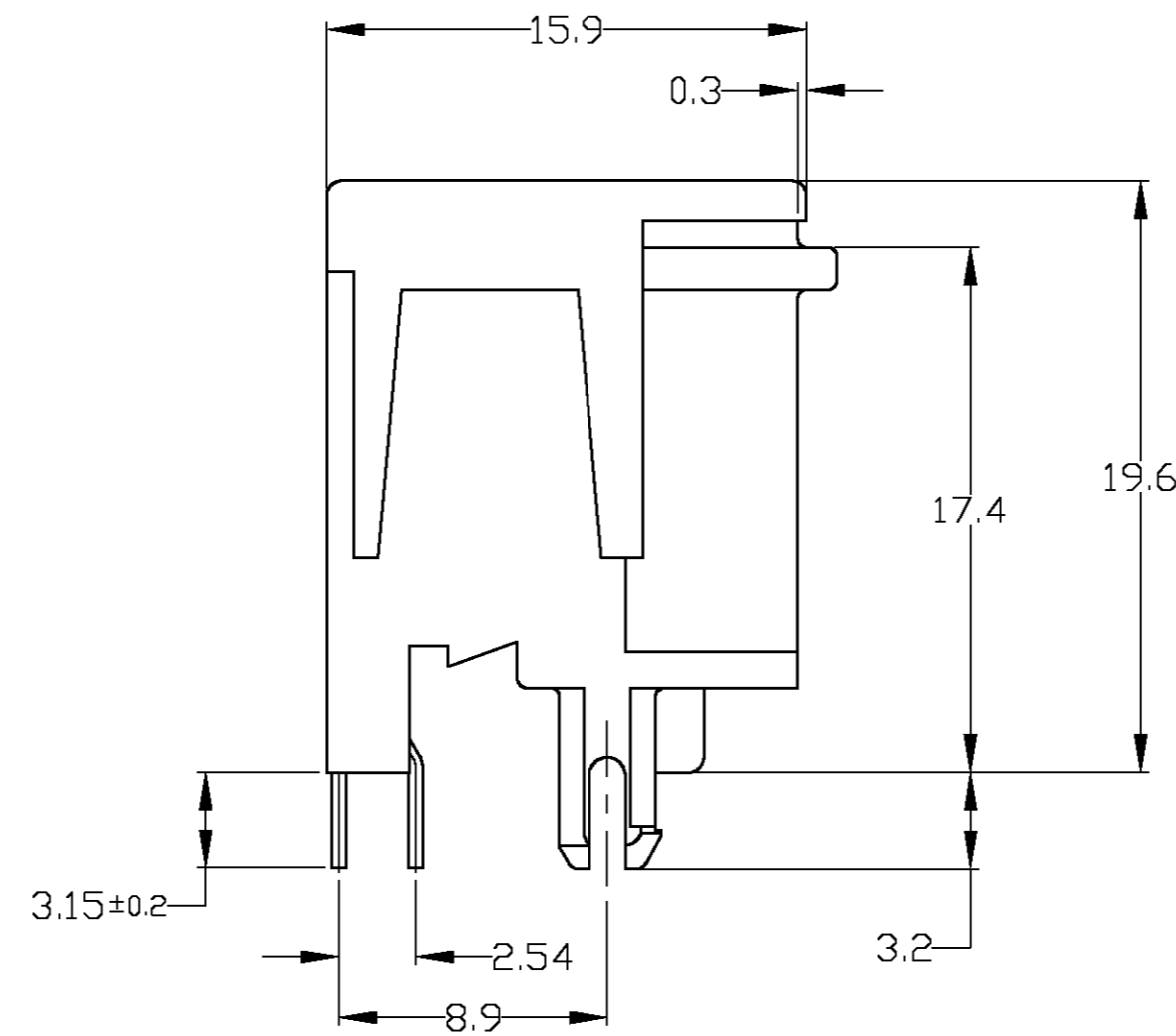
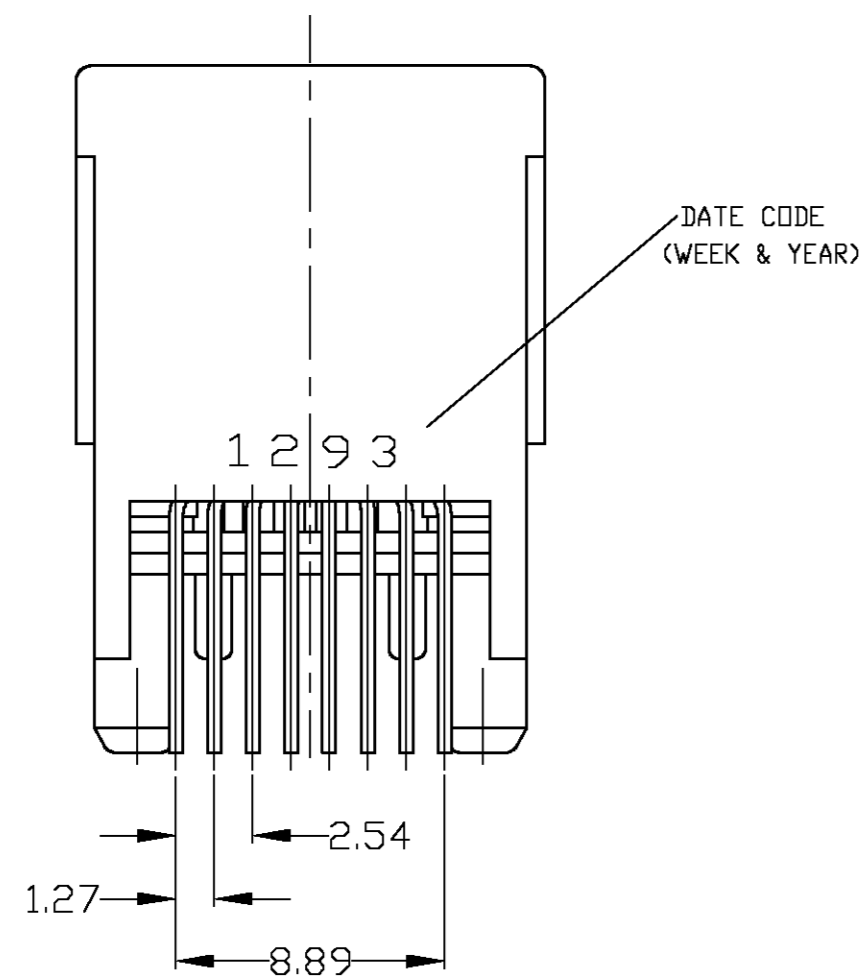


NOTES:

- 1 TOLERANCES UNLESS OTHERWISE SPECIFIED:  $\pm 0,15$ .
- 2 CONTACTS;  
1,27 $\mu$ m MIN. GOLD, SELECTIVE IN CONTACT AREA, OVER 1,27 $\mu$ m MIN. NICKEL.  
2,0  $\mu$ m MIN. TIN-LEAD OVER 1,27 $\mu$ m MIN. NICKEL ON SOLDER TINES.
- 3 HOUSING;  
PBT, COLOR BLACK, UL 94V-0  
CONTACTS;  
PHOSPHOR BRONZE.
- 4 FOR APPLICATION INFORMATION SEE AMP SPEC. 114-19019.
- 5 FOR PERFORMANCE REQUIREMENTS SEE AMP SPEC. 108-19064.
- 6 PACKAGING: BULK PACKAGED.  
TRUE POSITIONING OF THE SOLDER TINES,  
MAY BE AFFECTED BY BULK PACKAGING.

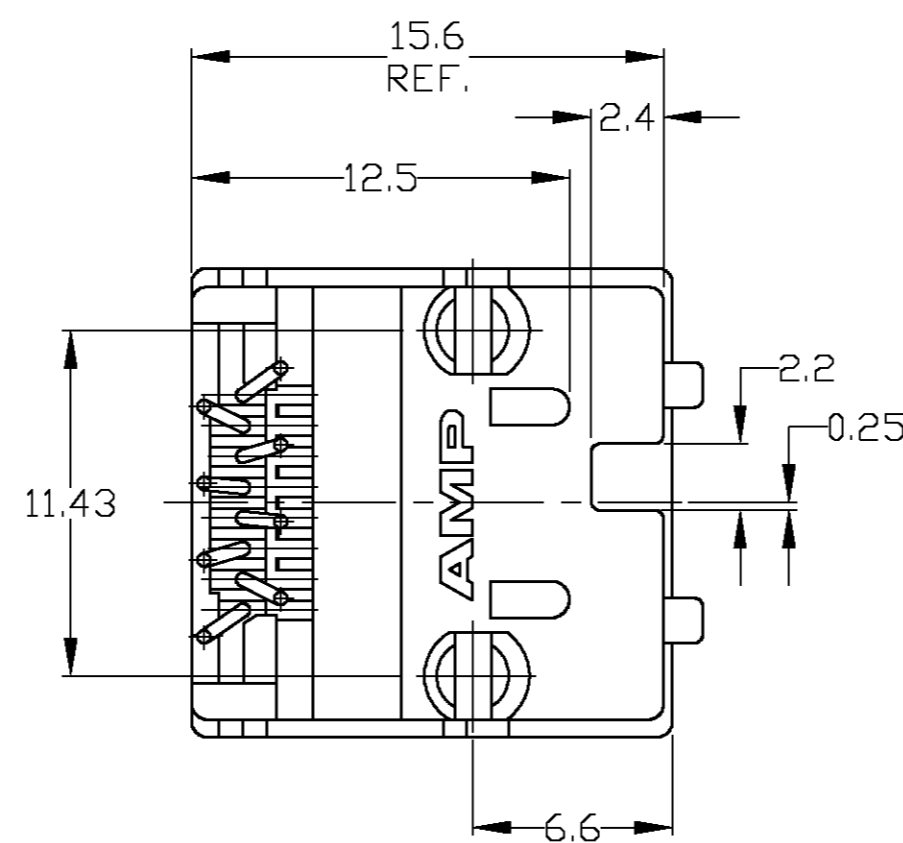


PRINTED CIRCUIT BOARD LAYOUT

[VIEW SHOWN IS CIRCUIT (NONCOMPONENT) SIDE OF BOARD.]

PRINTED CIRCUIT BOARD THICKNESS: 1,6 mm NOMINAL.

TOLERANCES UNLESS OTHERWISE SPECIFIED:  $\pm 0,05$ .



8 POS. / 8 CONT.		FINISH		MATERIAL		338360-1
DESCRIPTION		FINISH		MATERIAL		P/N
				CUSTOMER DRAWING		FOR REFERENCE ONLY WILL NOT BE UPDATED
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				THIS DRAWING IS UNPUBLISHED		RELEASED FOR PUBLICATION
B	SR10-00B4-02	KV	06 FEB 02	Tyco Electronics Corporation Oostkamp - BELGIUM		NAME MODULAR JACK, 8 POS., TOP ENTRY HIGH PROFILE, WITH SPECIAL PANEL STOPS FOR PRINTED CIRCUIT BOARD
A	EH-1142-97	EVE	W.B. 18 NOV 97			
O	EH-0870-97	EVE	W.B. 12 AUG 97			
LTR. REVISION RECORD		DR.	CHK.	DATE		
DR.: E.v.EJK	CHK.: W.BRUMMANS	APP.: R.SMEETS	DWG.No.		REV.LTR.	SHEET
DATE: 12 AUG 97	DATE:	DATE:	C-338360		B	1 OF 1